

**PRINTED CIRCUIT BOARD HAVING SOLDER BRIDGES FOR
ELECTRONICALLY CONNECTING CONDUCTING PADS AND
METHOD OF FABRICATING SOLDER BRIDGES**

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ABSTRACT OF THE DISCLOSURE

A method of fabricating a zero signal degradation solder bridge electrical connection for connecting adjacent conducting pads of a printed circuit board, and a printed circuit board having at least one of these solder bridge electrical connections. In the method, a stencil, having an opening that corresponds to the adjacent conducting pads and at least a portion of the surface area of the printed circuit board between the adjacent conducting pads, is placed on the surface of printed circuit board. Solder paste is then applied to the stencil such that the solder paste flows through the stencil opening and onto the adjacent conducting pads and at least a portion of the surface area of the printed circuit board between the pads. The stencil is then removed and the printed circuit board is subjected to reflow soldering, thereby fabricating a printed circuit board having a solder bridge electrical connector between adjacent conducting pads.